

## 150V N-Channel Enhancement Mode Power MOSFET

### Description

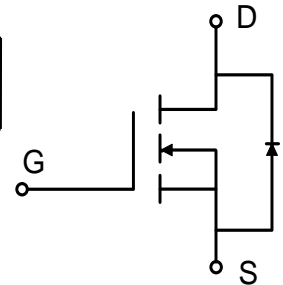
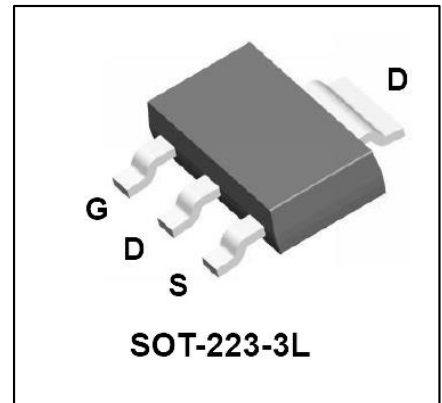
WMT04N15T1 uses advanced power trench technology that has been especially tailored to minimize the on-state resistance and yet maintain superior switching performance.

### Features

- $V_{DS} = 150V$ ,  $I_D = 4A$   
 $R_{DS(on)} < 160m\Omega @ V_{GS} = 10V$
- High Density Cell Design for Ultra Low  $R_{Dson}$
- Fully Characterized Avalanche Voltage and Current
- Excellent Package for Good Heat Dissipation

### Applications

- Power Switching Application
- Hard Switched and High Frequency Circuits



### Absolute Maximum Ratings

Parameter		Symbol	Value	Unit
Drain-Source Voltage		$V_{DS}$	150	V
Gate-Source Voltage		$V_{GS}$	$\pm 20$	V
Continuous Drain Current <sup>1</sup>	$T_C = 25^\circ C$	$I_D$	4	A
Pulsed Drain Current <sup>2</sup>		$I_{DM}$	16	A
Single Pulse Avalanche Energy <sup>3</sup>		<b>EAS</b>	8	mJ
Total Power Dissipation <sup>4</sup>	$T_C = 25^\circ C$	$P_D$	2.9	W
Operating Junction and Storage Temperature Range		$T_J, T_{STG}$	-55 to +150	$^\circ C$

### Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance from Junction-to-Ambient <sup>1</sup>	$R_{\theta JA}$	80	$^\circ C/W$

**Electrical Characteristics** T<sub>c</sub> = 25°C, unless otherwise noted

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
<b>Static Characteristics</b>						
Drain-Source Breakdown Voltage	<b>V<sub>(BR)DSS</sub></b>	V <sub>GS</sub> = 0V, I <sub>D</sub> = 250μA	150	-	-	V
Gate-body Leakage current	<b>I<sub>GSS</sub></b>	V <sub>DS</sub> = 0V, V <sub>GS</sub> = ±20V	-	-	±100	nA
Zero Gate Voltage Drain Current	<b>I<sub>DSS</sub></b>	T <sub>J</sub> =25°C V <sub>DS</sub> = 150V, V <sub>GS</sub> = 0V	-	-	1	μA
Gate-Threshold Voltage	<b>V<sub>GS(th)</sub></b>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250μA	1.5	2.0	2.5	V
Drain-Source On-Resistance <sup>2</sup>	<b>R<sub>DS(on)</sub></b>	V <sub>GS</sub> = 10V, I <sub>D</sub> = 4A	-	125	160	mΩ
<b>Dynamic Characteristics</b>						
Input Capacitance	<b>C<sub>iss</sub></b>	V <sub>DS</sub> = 25V, V <sub>GS</sub> = 0V, f = 1MHz	-	883	-	pF
Output Capacitance	<b>C<sub>oss</sub></b>		-	53	-	
Reverse Transfer Capacitance	<b>C<sub>rss</sub></b>		-	37	-	
<b>Switching Characteristics</b>						
Gate Resistance	<b>R<sub>g</sub></b>	V <sub>DS</sub> = 0V, V <sub>GS</sub> = 0V, f = 1MHz	-	1.1	-	Ω
Total Gate Charge	<b>Q<sub>g</sub></b>	V <sub>GS</sub> = 10V, V <sub>DS</sub> = 75V, I <sub>D</sub> = 1.5A	-	18.5	-	nC
Gate-Source Charge	<b>Q<sub>gs</sub></b>		-	5.3	-	
Gate-Drain Charge	<b>Q<sub>gd</sub></b>		-	6.9	-	
Turn-On Delay Time	<b>t<sub>d(on)</sub></b>	V <sub>GS</sub> = 10V, V <sub>DS</sub> = 75V R <sub>G</sub> = 6Ω, I <sub>D</sub> = 1A, R <sub>L</sub> = 75Ω	-	7.9	-	nS
Rise Time	<b>t<sub>r</sub></b>		-	9.8	-	
Turn-Off Delay Time	<b>t<sub>d(off)</sub></b>		-	19.5	-	
Fall Time	<b>t<sub>f</sub></b>		-	14.7	-	
<b>Drain-Source Body Diode Characteristics</b>						
Diode Forward Voltage <sup>2</sup>	<b>V<sub>SD</sub></b>	I <sub>S</sub> = 2A, V <sub>GS</sub> = 0V	-	-	1.2	V
Continuous Source Current <sup>1,5</sup>	<b>I<sub>S</sub></b>	V <sub>G</sub> =V <sub>D</sub> =0V, Force Current	-	-	4	A

## Notes:

1. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
2. The data tested by pulsed, pulse width ≤ 300us, duty cycle ≤ 2%
3. The EAS data shows Max. rating. The test condition is V<sub>DD</sub>=25V, V<sub>GS</sub>=10V, L=1mH. I<sub>AS</sub>=4A
4. The power dissipation is limited by 150°C junction temperature
5. The data is theoretically the same as I<sub>D</sub> and I<sub>DM</sub>, in real applications, should be limited by total power dissipation.

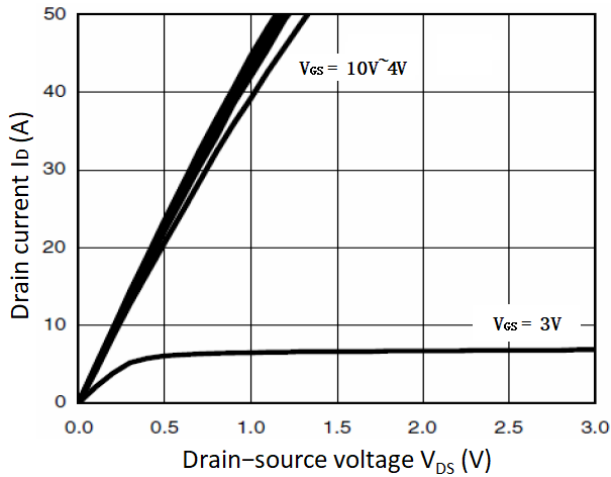


Figure 1. Typical Output Characteristics

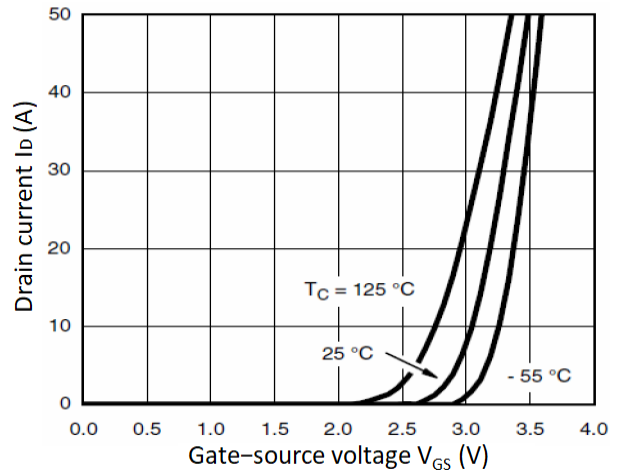


Figure 2. Transfer Characteristics

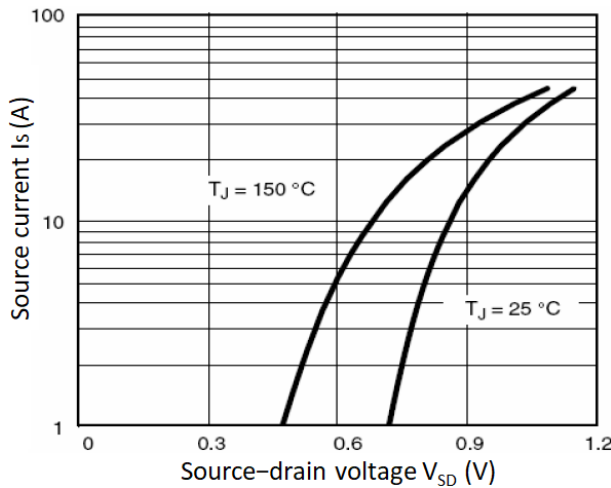


Figure 3. Forward Characteristics of Reverse

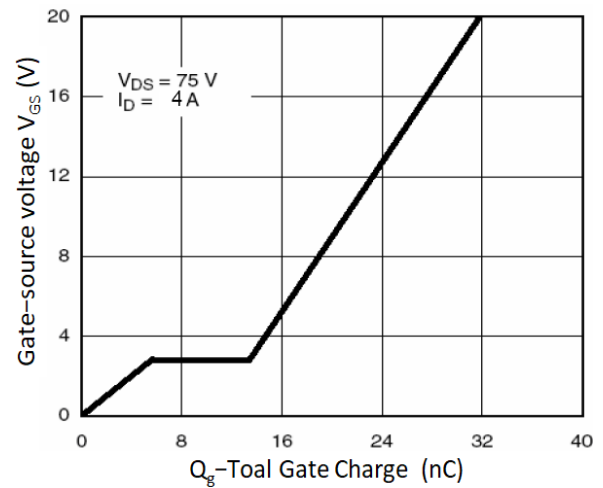


Figure 4. Gate Charge Characteristics

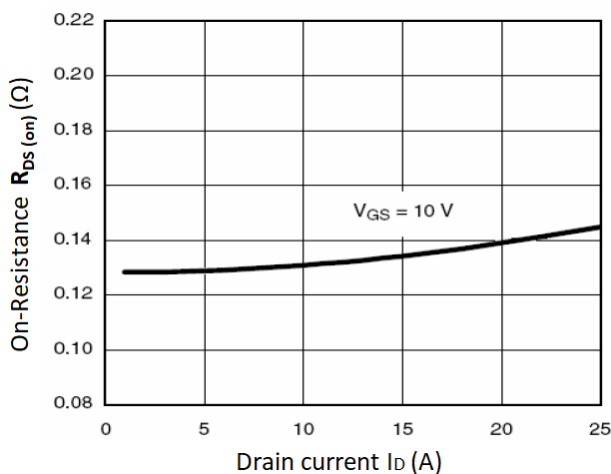


Figure 5.  $R_{DS(on)}$  vs.  $I_D$

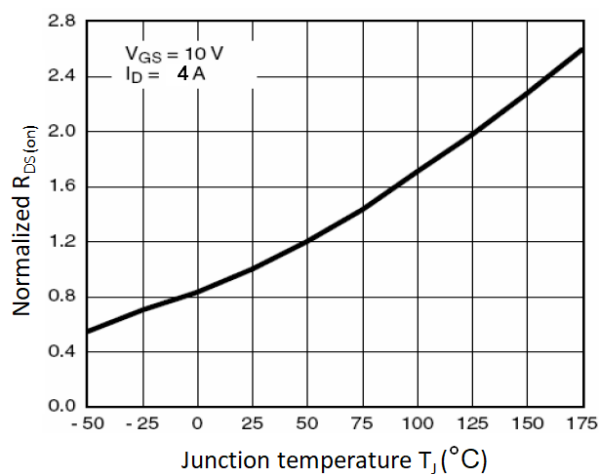


Figure 6. Normalized  $R_{DS(on)}$  vs.  $T_J$

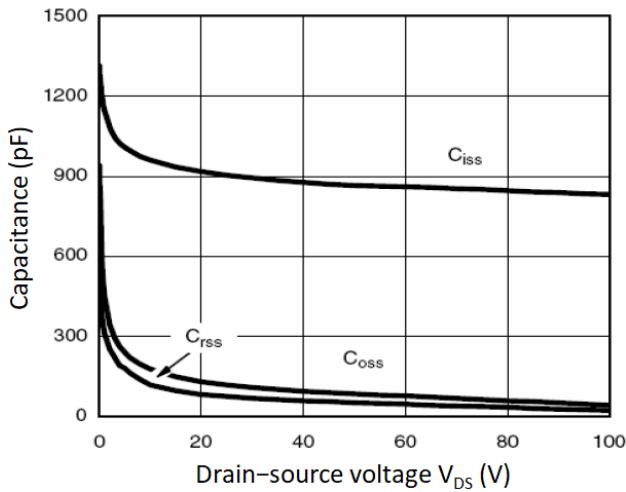


Figure 7. Capacitance Characteristics

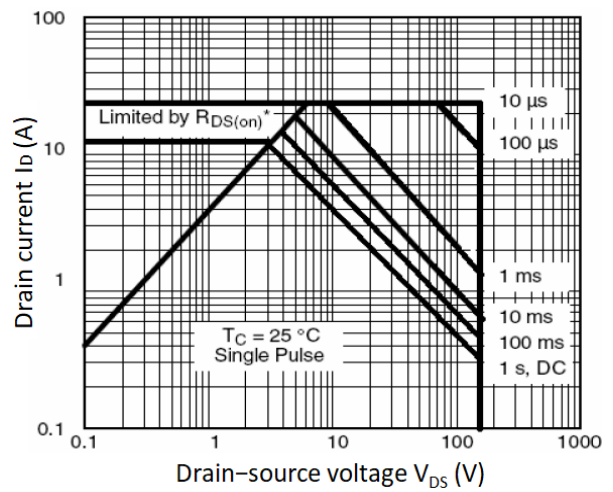


Figure 8. Safe Operating Area

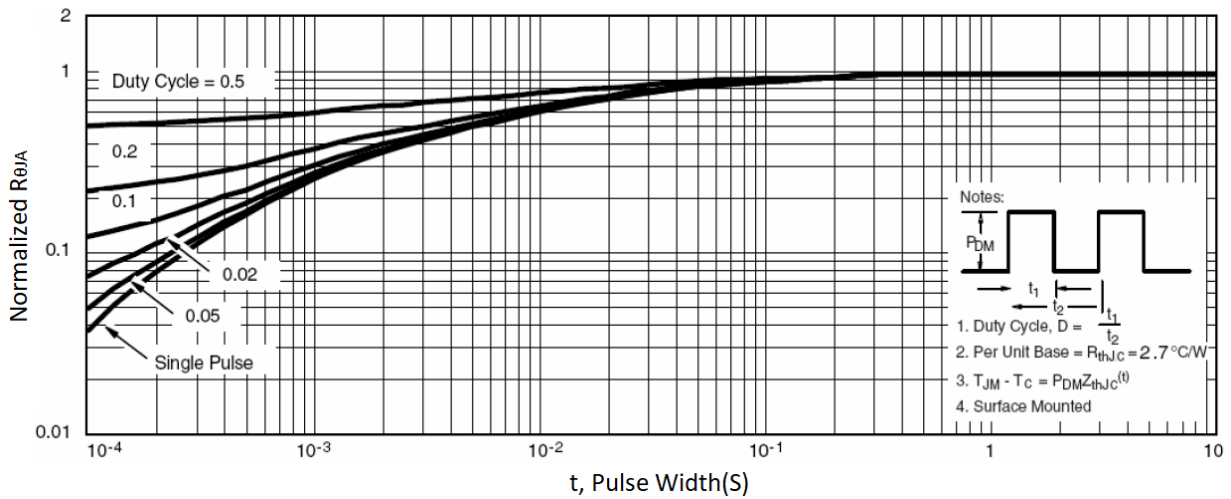


Figure 9. Normalized Maximum Transient Thermal Impedance

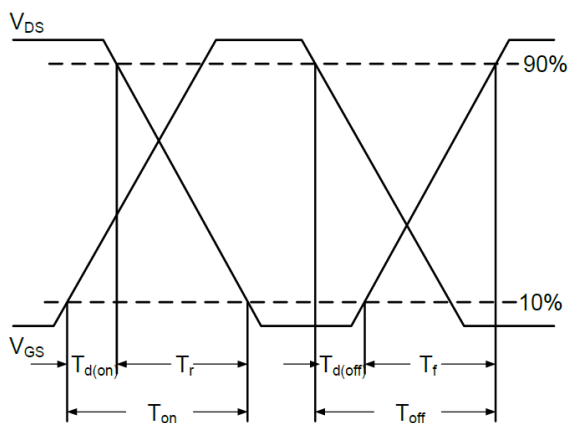


Figure 10. Switching Time Waveform

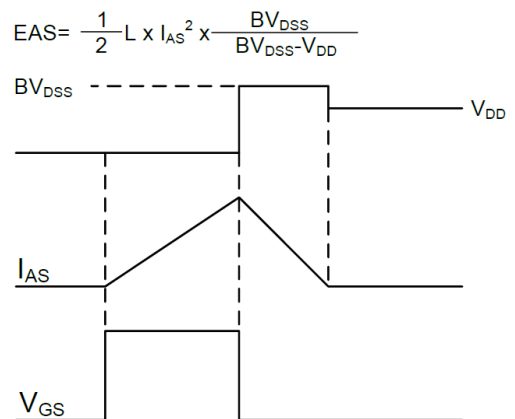
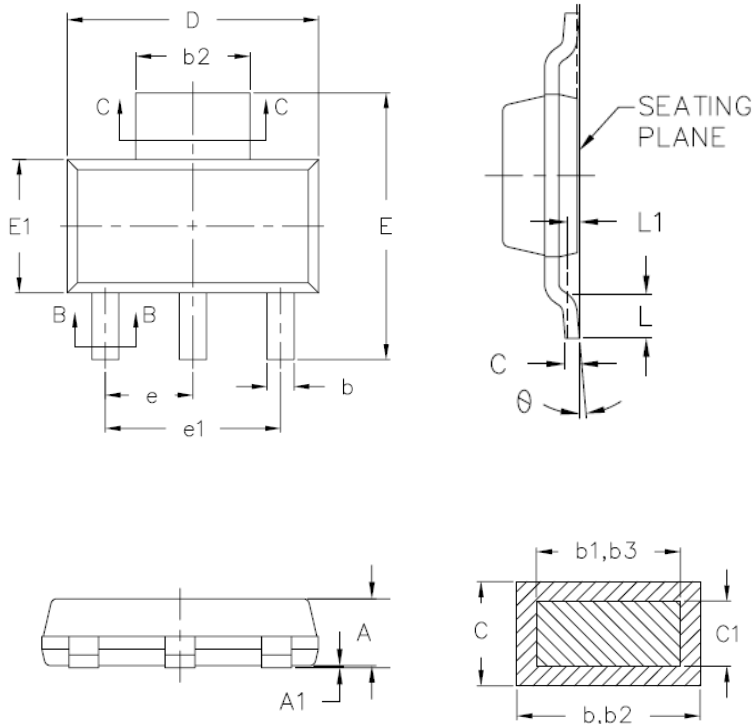


Figure 11. Unclamped Inductive Switching Waveform

## Mechanical Dimensions for SOT-223-3L



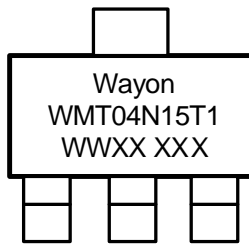
## COMMON DIMENSIONS

SYMBOL	MM	
	MIN	MAX
A	-	1.80
A1	0.02	0.10
b	0.66	0.84
b1	0.60	0.79
b2	2.90	3.10
b3	2.84	3.05
c	0.23	0.35
c1	0.23	0.33
D	6.20	6.70
E	6.70	7.30
E1	3.30	3.70
e	2.30BSC	
e1	4.60BSC	
L	0.80	-
L1	0.25BSC	
θ	0°	10°

## Ordering Information

Part	Package	Marking	Packing method
WMT04N15T1	SOT-223-3L	WMT04N15T1	Tape and Reel

## Marking Information



WMT04N15T1 = Device code

WWXX XXX= Date code

## Contact Information

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